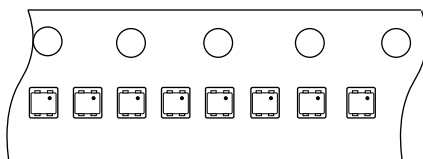
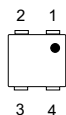
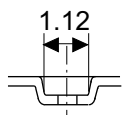
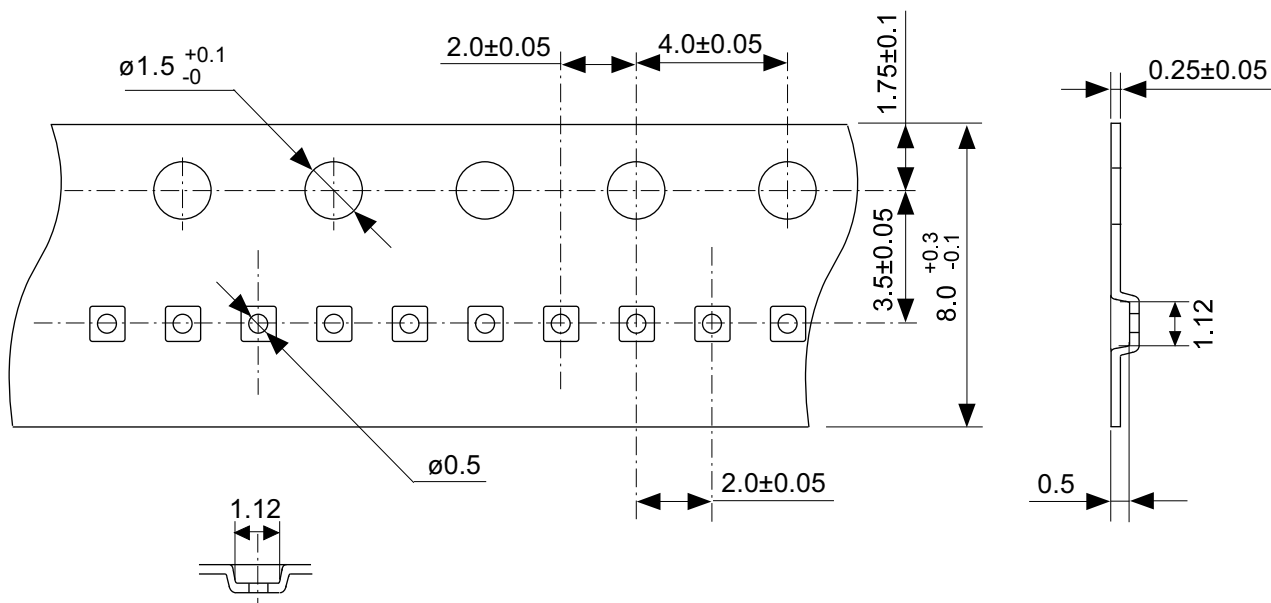


※ The heat sink of back side has different electric potential depending on the product.  
 Confirm specifications of each product.  
 Do not use it as the function of electrode.

No. PL004-B-P-SD-1.0

TITLE	HSNT-4-D-PKG Dimensions
No.	PL004-B-P-SD-1.0
ANGLE	
UNIT	mm
<b>ABLIC Inc.</b>	

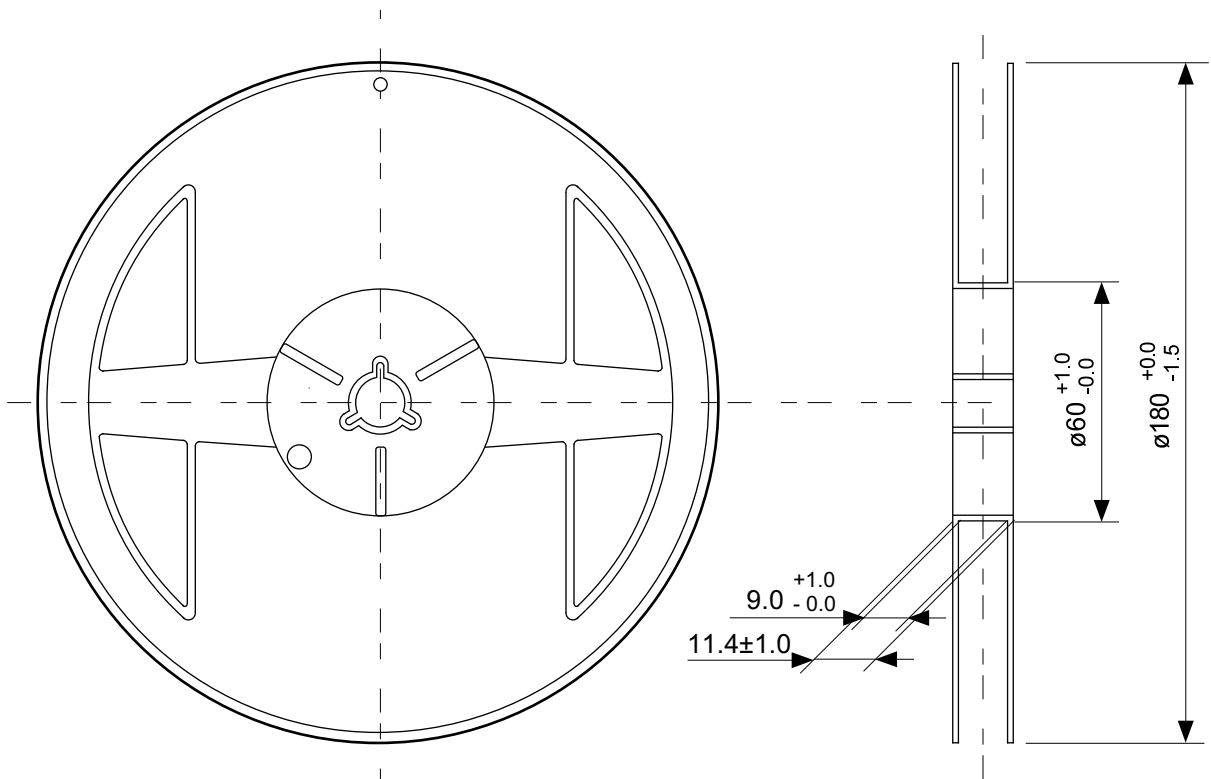


Feed direction

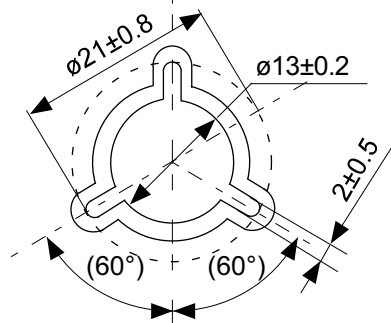
No. PL004-B-C-SD-1.0

TITLE	HSNT-4-D-Carrier Tape
No.	PL004-B-C-SD-1.0
ANGLE	
UNIT	mm
<b>ABLIC Inc.</b>	

The information herein is subject to change without notice.



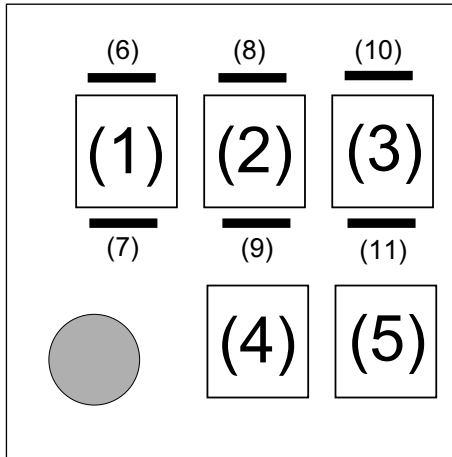
Enlarged drawing in the central part



No. PL004-B-R-SD-1.0

TITLE	HSNT-4-D-Reel		
No.	PL004-B-R-SD-1.0		
ANGLE		QTY.	10,000
UNIT	mm		
<b>ABLIC Inc.</b>			

The information herein is subject to change without notice.



PKG PIN#1

(1) to (3) : Product code

(4), (5) : Lot No.

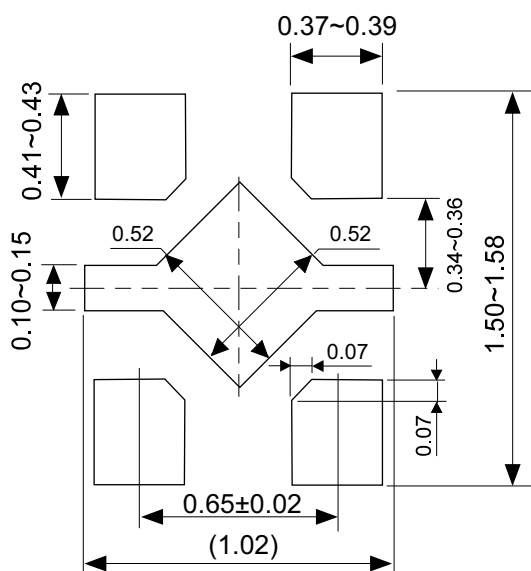
(6), (7) : Year of assembly (bar)

(8) to (11): Month of assembly (bar)

No. PL004-B-M-SD-1.0

TITLE	HSNT-4-D-Markings		
No.	PL004-B-M-SD-1.0		
ANGLE			
UNIT		TYPE	LASER
<b>ABLIC Inc.</b>			

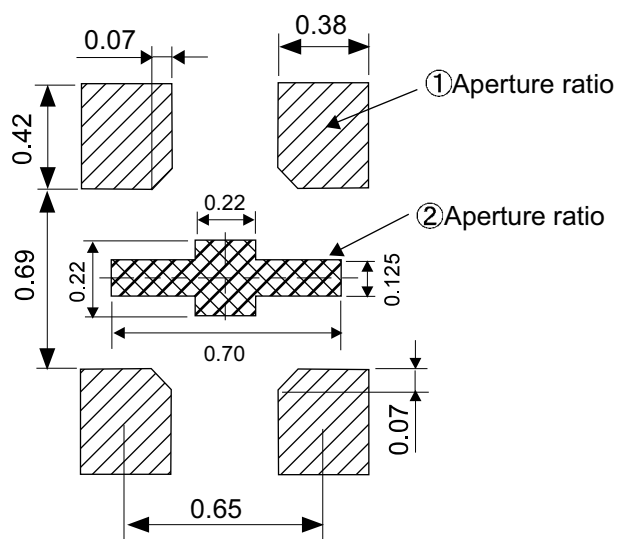
## Land Pattern



Caution It is recommended to solder the heat sink to a board in order to ensure the heat radiation.

注意 放熱性を確保する為に、PKGの裏面放熱板(ヒートシンク)を基板に半田付けする事を推奨いたします。

## Metal Mask Pattern



Caution ① Mask aperture ratio of the lead mounting part is 100%.  
 ② Mask aperture ratio of the heat sink mounting part is approximately 40%.  
 ③ Mask thickness:  $t0.12$  mm

注意 ①リード実装部のマスク開口率は100%です。  
 ②放熱板実装のマスク開口率は約40%です。  
 ③マスク厚み:  $t 0.12$  mm

No. PL004-B-L-SD-1.0

TITLE	HSNT-4-D -Land Recommendation
No.	PL004-B-L-SD-1.0
ANGLE	
UNIT	mm
<b>ABLIC Inc.</b>	